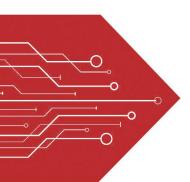
## MSKSEMI















**ESD** 

TVS

TSS

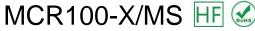
MOV

GDT

**PLED** 

# Broduct data sheet













1.KATHODE

2.ANODE

3.GATE

**SOT-89** 

#### **FEATURES**

Current-I<sub>GT</sub>: 200 µA

I<sub>TRMS</sub>: 0.8 A

 $V_{RRM}/V_{DRM}$ : MCR100-6/MS: 400 V

MCR100-8/MS: 600 V

Operating and storage junction temperature range



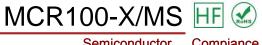
### ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Syı	mbol	Test conditions	Min	Max	Unit
On state voltage	\	/ <sub>TM</sub> *	I <sub>TM</sub> =1A		1.7	V
Gate trigger voltage	$V_{GT}$		V <sub>AK</sub> =7V		0.8	V
Peak Repetitive forward and reverse blocking voltage  MCR100-6  MCR100-8	V <sub>DRM</sub> and V <sub>RRM</sub>		I <sub>DRM</sub> = 10 μA	400 600		V
Peak forward or reverse blocking Current	I <sub>DRM</sub> I <sub>RRM</sub>		V <sub>AK</sub> = Rated V <sub>DRM</sub> or V <sub>RRM</sub>		10	μΑ
Holding current			I <sub>HL</sub> = 20mA ,Vaк = 7V		5	mA
Gate trigger current	Іст	A2	V <sub>AK</sub> =7V	5	15	μΑ
		A1		15	30	μΑ
		А		30	80	μΑ
		В		80	200	μΑ

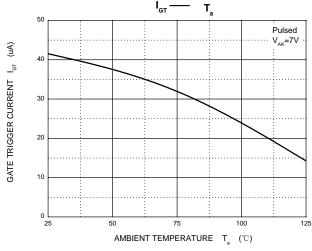
<sup>\*</sup> Forward current applied for 1 ms maximum duration, duty cycle≤1%.

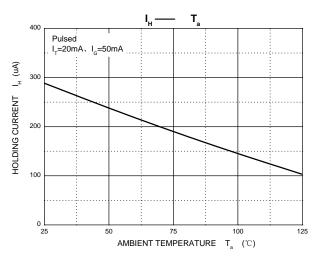


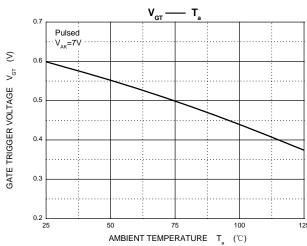


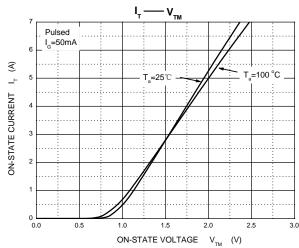


## **Typical Characteristics**



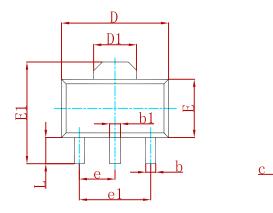


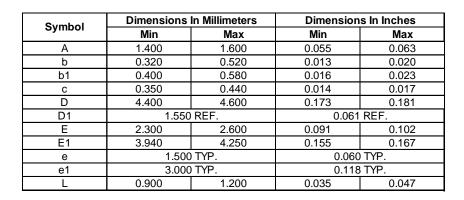




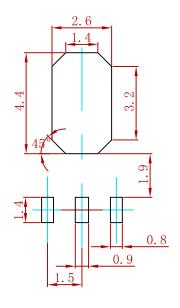


#### **PACKAGE MECHANICAL DATA**





## **Suggested Pad Layout**



#### Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
MCR100-X/MS	SOT-89	1000



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